

GSDSS3□□A1F Series

Schottky Barrier Diode

Product Description

Reverse Voltage 40V to 200V.
Forward Current 3.0A



Features

- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- RoHS Compliant and Halogen Free

Mechanical Data

- Case : Molded Plastic, SMAF Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Polarity: Color Band denotes Cathode End

Package and Pin Assignment

SMAF		Equivalent Circuit
		
Pin	Description	
1	Anode	
2	Cathode	

Ordering and Marking Information

Ordering Information			
Part Number	Package	Marking Code	Quantity/Reel
GSDSS34A1F	SMAF	SS34F	3000 PCS
GSDSS36A1F	SMAF	SS36F	3000 PCS
GSDSS310A1F	SMAF	SS310F	3000 PCS
GSDSS315A1F	SMAF	SS315F	3000 PCS
GSDSS320A1F	SMAF	SS320F	3000 PCS

GSDSS3 □ □ A1 F		
- Product Code: GSDSS3	- Voltage Code: □ □ is 4, 6, 10, 15 and 20. For examples 4 stands for 40V and 20 stands for 200V	- Package Code: A1 for SMAF Package
- Green Level: F for RoHS Compliant and Halogen Free		

Marking Information

SS3 □□ F

- **Product Code:**
SS3

- **Voltage Code:**
□□ is 4, 6, 10, 15 and 20.
For examples 4 stands for 40V
and 20 stands for 200V

- **Green Level:**
F for RoHS Compliant and
Halogen Free

Electrical Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60HZ, resistive or inductive load. For capacitive load, derate current by 20%.)

Symbol	Description	34A1F	36A1F	310A1F	315A1F	320A1F	Unit
V _{RRM}	Maximum Repetitive Peak Reverse Voltage	40	60	100	150	200	V
V _{RMS}	Maximum RMS Voltage	28	42	70	105	140	V
V _{DC}	Maximum DC Blocking Voltage	40	60	100	150	200	V
I _(AV)	Maximum Average Forward Rectified Current	3.0					A
I _{FSM}	Peak Forward Surge Current, 8.3ms Single Half-Sine-Wave Superimposed on rated Load (JEDEC Method)	80					A
V _F	Maximum Forward Voltage at 3.0A	0.55	0.70	0.85	0.95	V	
I _R	Maximum Reverse Current at Rated DC Blocking Voltage T _A =25°C	0.5		0.2		mA	
	T _A =100°C	20.0		10.0		mA	
C _J	Typical Junction Capacitance ⁽¹⁾	550	320			pF	
R _{θJA}	Typical Thermal Resistance ¹	65					°C/W
T _J	Junction Temperature Range	-65 to 125		-65 to 150		°C	
T _{STG}	Storage Temperature Range	-65 to 150					°C

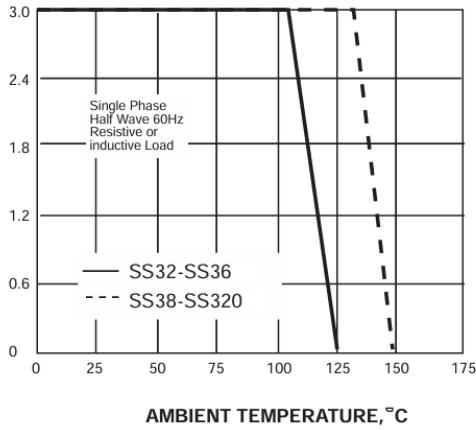
NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0 V_{DC}.
2. Mounted with 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Areas

Typical Characteristics (Ratings at 25°C Ambient Temperature Unless Otherwise Specified.)

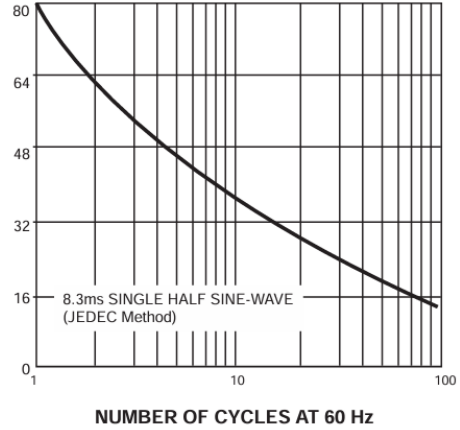
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



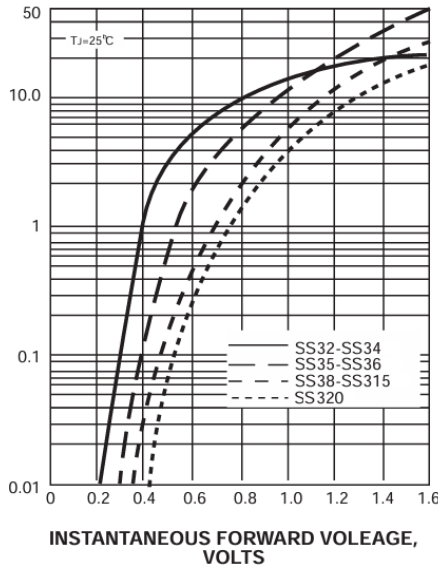
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



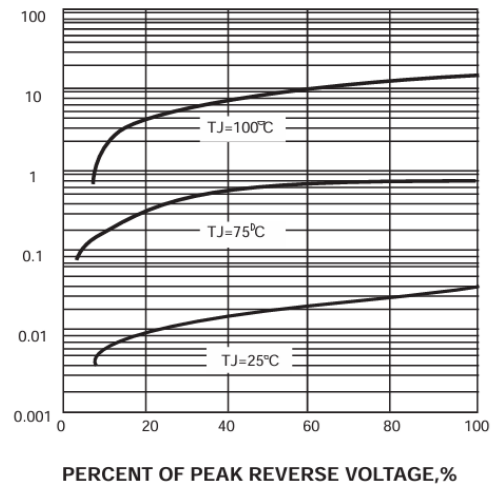
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



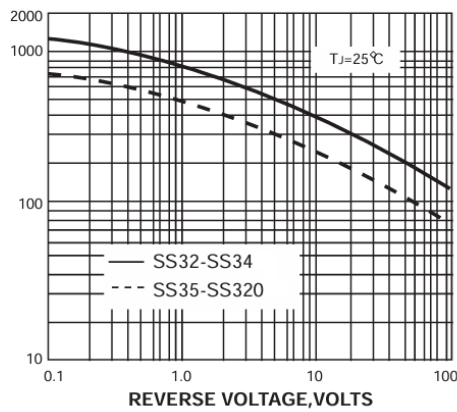
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



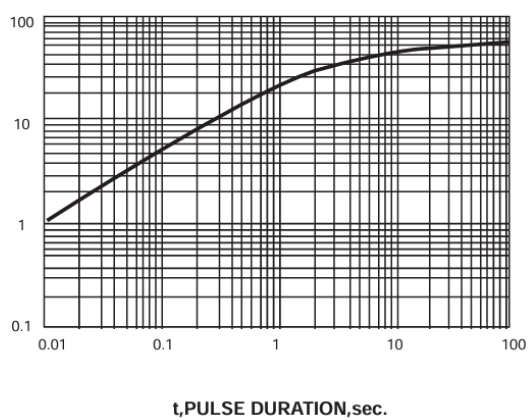
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



TRANSIENT THERMAL IMPEDANCE, °C/W

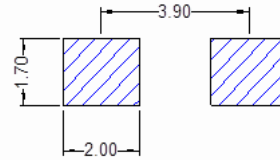
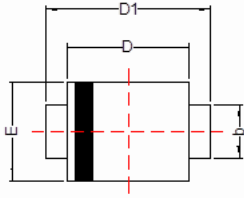
FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



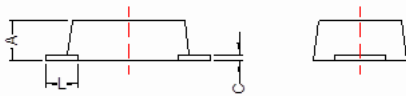
SMAF

Package Dimension

Recommended Land Pattern



(Unit: mm)







Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.90	1.30	0.035	0.051
b	1.20	1.60	0.047	0.063
D	3.25	3.75	0.128	0.147
D1	4.30	4.90	0.169	0.193
E	2.30	2.70	0.091	0.106
c	0.05	0.3	0.002	0.012
L	1.20 MAX		0.047 MAX	



NOTE:
Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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